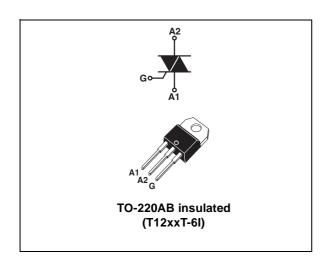


## Snubberless™, logic level and standard 12 A Triacs

Datasheet - production data



**Table 1. Device summary** 

Part number	Symbol	Value
T1210T-6I	I <sub>GT</sub> 3Q logic level	10 mA
T1220T-6I T1235T-6I	I <sub>GT</sub> 3Q Snubberless	20 / 35 mA
T1225T-6I	I <sub>GT</sub> 4Q standard	25 mA

### **Features**

- Medium current Triac
- High static and dynamic commutation
- · Low thermal resistance with clip bonding
- Packages is RoHS (2002/95/EC) compliant
- 600 V V<sub>RM</sub>
- UL certified (ref. file E81734)

### **Applications**

- Value sensitive application
- · General purpose ac line load switching
- Motor control circuits in power tools
- · Small home appliances, lighting
- Inrush current limiting circuits
- · Overvoltage crowbar protection

### **Description**

Available in through-hole, the T12T series of Triacs can be used as on/off or phase angle control function in general purpose AC switching where high commutation capability is required.

This series can be designed in many value sensitive appliances thanks to the parameters guidance provided in the following pages.

Provides insulation rated at 2500 V rms (TO-220AB insulated package).

TM: Snubberless is a trademark of STMicroelectronics

Characteristics T12T

# 1 Characteristics

Table 2. Absolute maximum ratings (limiting values;  $T_j = 25$  °C, unless otherwise specified)

Symbol	Parameter				Unit
I <sub>T(RMS)</sub>	On-state rms current (full sine wave)		T <sub>c</sub> = 88 °C	12	Α
1 .	Non repetitive surge peak on-state current (full	F = 50 Hz	t <sub>p</sub> = 20 ms	90	Α
I <sub>TSM</sub>	cycle, T <sub>j</sub> initial = 25 °C)	F = 60 Hz	$t_p = 16.7 \text{ ms}$	95	А
l <sup>2</sup> t	I <sup>2</sup> t Value for fusing	t <sub>p</sub> = 10 ms		54	A <sup>2</sup> s
dI/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$ $F = 60 \text{ Hz}$ $T_j = 125 \text{ °C}$		50	A/µs	
V <sub>DSM</sub> , V <sub>RSM</sub>	Non repetitive surge peak off-state voltage	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	V <sub>DRM</sub> , V <sub>RRM</sub> + 100	V
I <sub>GM</sub>	Peak gate current $t_p = 20 \mu s$ $T_j = 125 °C$		4	Α	
P <sub>G(AV)</sub>	Average gate power dissipation $T_j = 125$ °C			1	W
T <sub>stg</sub>	Storage junction temperature range			- 40 to + 150	°C
Tj	Operating junction temperature range			- 40 to + 125	°C



T12T Characteristics

Table 3. Electrical characteristics ( $T_j = 25$  °C, unless otherwise specified)

Cumbal	Toot conditions	Quadrant		T12xxT			11	
Symbol	Test conditions	Quadrant		T1210T	T1220T	T1225T	T1235T	Unit
I <sub>GT</sub> <sup>(1)</sup>	$V_D = 12 \text{ V}  R_L = 30 \Omega$	I - II - III	MAX.	10	20	25	35	mA
'GT`		IV				40		
V <sub>GT</sub>	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega,$ ALL MAX. 1.3			V				
V <sub>GD</sub>	$V_D = V_{DRM}, R_L = 3.3 \text{ k}\Omega,$ $T_j = 125 \text{ °C}$	ALL	MIN.	0.2		V		
I <sub>H</sub> <sup>(2)</sup>	I <sub>T</sub> = 500 mA		MAX.	10	15	20	30	mA
	I <sub>G</sub> = 1.2 I <sub>GT</sub>	I - III		20	35	40	50	mA
IL		IV	MAX.			40		
		II		30	40	60	80	
dV/dt (2)	V <sub>D</sub> = 67% V <sub>DRM,</sub> gate open	T <sub>j</sub> = 125 °C	MIN.	100	1000	100	2000	1//110
u v/ui · ·		$T_j = 150  {}^{\circ}C^{(3)}$	IVIIIN.	50	500	50	1000	V/µs
	$(dV/dt)c = 0.1 V/\mu s$			7		7		
	(dV/dt)c = 10 V/µs	T <sub>j</sub> = 125 °C		3		3		
(dl/dt)c (2)	Without snubber		MIN.		6		12	A/ms
	$(dV/dt)c = 0.1 V/\mu s$		IVIIIN.	3		3		A/1119
	(dV/dt)c = 10 V/µs	$T_j = 150  {}^{\circ}C^{(3)}$		1		1		
	Without snubber				3		10	

- 1. Minimum  $I_{\mbox{\footnotesize GT}}$  is guaranteed at 5% of  $I_{\mbox{\footnotesize GT}}$  max.
- 2. For both polarities of A2 referenced to A1.
- 3. Derating information for excess temperature above  $T_j$  max.

**Table 4. Static characteristics** 

Symbol	Test conditions			Value	Unit
V <sub>T</sub> <sup>(1)</sup>	$I_{TM} = 17 \text{ A}, t_p = 380 \ \mu \text{s}$	T <sub>j</sub> = 25 °C	MAX.	1.55	V
V <sub>TO</sub> (1)	Threshold voltage	T <sub>j</sub> = 125 °C	MAX.	0.85	V
R <sub>D</sub> <sup>(1)</sup>	Dynamic resistance	T <sub>j</sub> = 125 °C	MAX.	35	mΩ
I <sub>DRM</sub> I <sub>RRM</sub>	$V_{DRM} = V_{RRM}$	T <sub>j</sub> = 25 °C	MAX.	5	μΑ
		T <sub>j</sub> = 125 °C		1	A
	$V_D = 0.9 \times V_{DRM}$	$T_j = 150  {}^{\circ}C^{(2)}$	TYP.	1.9	mA

- 1. For both polarities of A2 referenced to A1.
- 2. Derating information for excess temperature above  $\boldsymbol{T}_{j}\,\boldsymbol{max}.$

Characteristics T12T

Table 5. Thermal resistance

Symbol	Parameter	Value	Unit
R <sub>th(j-c)</sub>	Junction to case (AC)	2.6	°C/W
R <sub>th(j-a)</sub>	Junction to ambient (DC)	60	°C/W

Figure 1. Maximum power dissipation versus rms on-state current (full cycle)

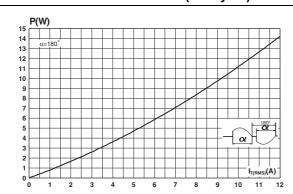


Figure 2. On-state rms current versus case temperature (full cycle)

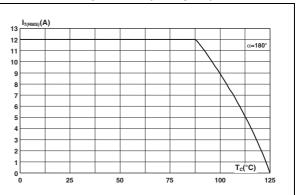
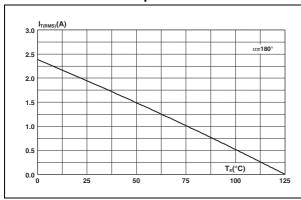


Figure 3. On-state rms current versus ambient temperature

Figure 4. Relative variation of thermal impedance versus pulse duration



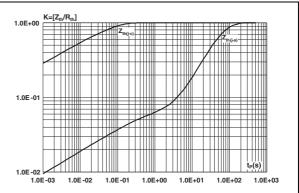
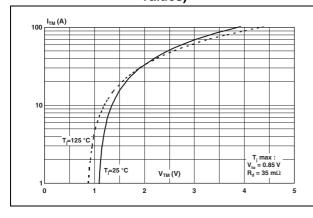
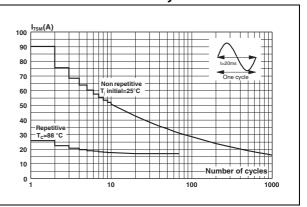


Figure 5. On state characteristics (maximum values)

Figure 6. Surge peak on state current versus number of cycles





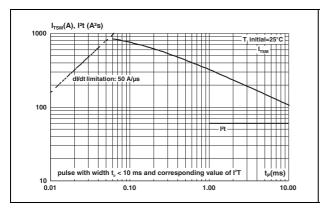
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T12T Characteristics

Figure 7. Non repetitive surge peak on state current for a sinusoidal

Figure 8. Relative variation of gate trigger current and gate trigger voltage versus junction temperature



2.5 typical values

2.6 typical values

2.7 typical values

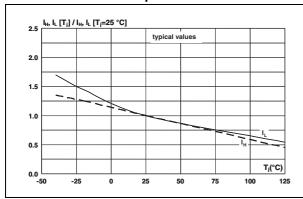
2.8 typical values

2.9 typical values

2.0 ty

Figure 9. Relative variation of holding current and latching current versus junction temperature

Figure 10. Relative variation of critical rate of decrease of main current versus (dV/dt)c



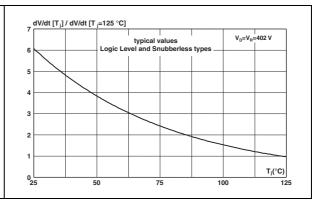
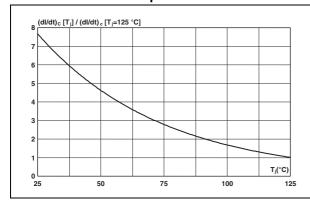
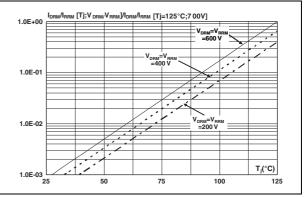


Figure 11. Relative variation of critical rate of decrease of main current versus junction temperature

Figure 12. Leakage current versus junction temperature for different values of blocking voltage (typical values)





Package information T12T

## 2 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

**Dimensions** Ref. **Millimeters** Inches Min. Тур. Max. Min. Тур. Max. Α 15.20 15.90 0.598 0.625 a1 3.75 0.147 a2 13.00 14.00 0.511 0.551 Ø١ 10.40 0.393 0.409 В 10.00 ÎL 0.024 b1 0.61 0.88 0.034 1.23 0.048 0.051 b2 1.32 14 С 4.40 4.60 0.173 0.181 0.027 0.49 0.70 0.019 с1 c2 2.72 0.107 2.40 0.094 a2 0.094 0.106 е 2.40 2.70 F 6.20 6.60 0.244 0.259 0.151 Ø١ 3.75 3.85 0.147 14 15.80 16.40 16.80 0.622 0.646 0.661 L 2.65 2.95 0.104 0.116 12 1.14 1.70 0.044 0.066 13 1.14 1.70 0.044 0.066 Μ 2.60 0.102

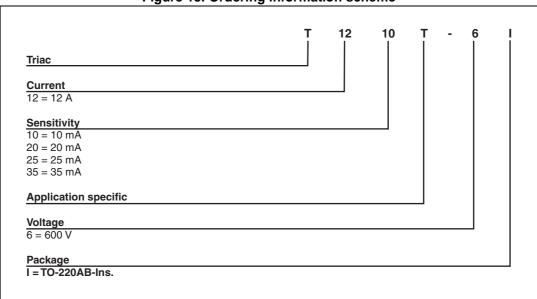
Table 6. TO-220AB insulated dimensions



T12T Ordering information

# 3 Ordering information

Figure 13. Ordering information scheme



**Table 7. Ordering information** 

Order code	Marking	Package	Weight	Base qty	Delivery mode
T1210T-6I	T1210T-6I				
T1220T-6I	T1220T-6I	TO-220AB-ins. 2.3 g		50	Tube
T1225T-6I	T1225T-6I	10-220AB-IIIs.	2.3 g	50	Tube
T1235T-6I	T1235T-6I				

# 4 Revision history

**Table 8. Document revision history** 

Date	Revision	Changes
03-Dec-2009	1	Initial release.
18-Jan-2010	2	Updated pag.1.
16-Sep-2013	3	Updated: Features. Replaced order codes with part numbers in Table 1.



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